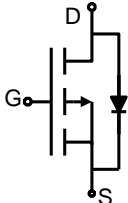
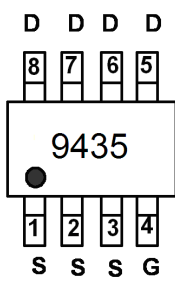
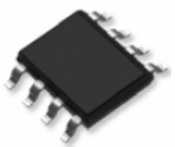


## P-Channel Enhancement Mode Power MOSFET

<p><b>DESCRIPTION</b></p> <p>The JRM9435 uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.</p> <p><b>GENERAL FEATURES</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS} = -30V, I_D = -5.1A</math></li> <li>● <math>R_{DS(ON)} &lt; 95m\Omega @ V_{GS} = -4.5V</math></li> <li>● <math>R_{DS(ON)} &lt; 65m\Omega @ V_{GS} = -10V</math></li> <li>● High Power and current handling capability</li> <li>● Lead free product is acquired</li> <li>● Surface Mount Package</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● PWM applications</li> <li>● Load switch</li> <li>● Power management</li> </ul>	<div style="text-align: center;">  <p>Schematic diagram</p>  <p>Marking and pin Assignment</p>  <p>SOP-8 top view</p> </div>
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### Package Marking And Ordering Information

Device Marking	Ordering Codes	Package	Product Code	Packing
M9435	JRM9435	SOP-8	JRM9435	Reel

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	±20	V
Drain Current-Continuous	$I_D$	-5.1	A
Drain Current-Pulsed (Note 1)	$I_{DM}$	-20	A
Maximum Power Dissipation	$P_D$	2.5	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	50	°C/W
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### Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30	-33	-	V

Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-24V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1	-1.6	-3	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-5.1A$	-	48	65	m $\Omega$
		$V_{GS}=-4.5V, I_D=-4.2A$	-	70	95	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS}=-15V, I_D=-4.5A$	4	7	-	S
<b>Dynamic Characteristics (Note4)</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=-15V, V_{GS}=0V,$ $F=1.0MHz$	-	1040	-	PF
Output Capacitance	$C_{oss}$		-	420	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	150	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V, I_D=-1A,$ $V_{GS}=-10V, R_{GEN}=6\Omega$	-	15	-	nS
Turn-on Rise Time	$t_r$		-	13	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	58	-	nS
Turn-Off Fall Time	$t_f$		-	21	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-15V, I_D=-5.1A, V_{GS}=-10V$	-	12	-	nC
Gate-Source Charge	$Q_{gs}$		-	2.2	-	nC
Gate-Drain Charge	$Q_{gd}$		-	3	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	$V_{SD}$	$V_{GS}=0V, I_S=-1.7A$	-	-	-1.2	V

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

Figure 1 Output Characteristics

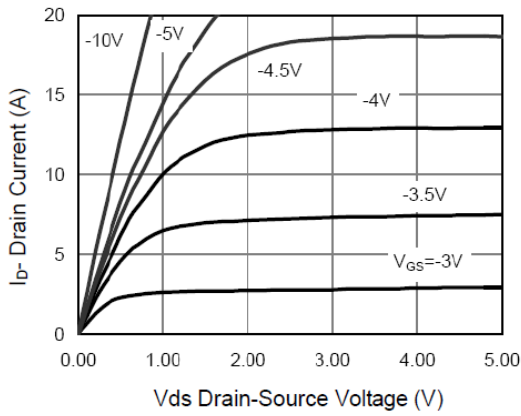


Figure 2 Transfer Characteristics

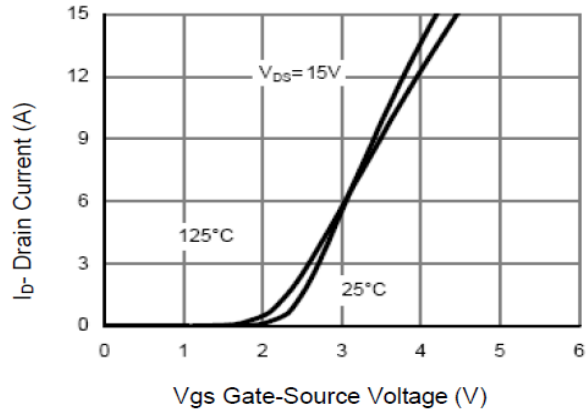


Figure 3 On-Resistance vs.  $I_D$  and  $V_{GS}$

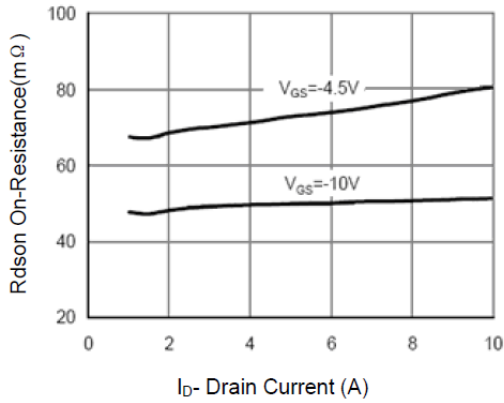


Figure 4 On-Resistance vs. Junction Temperature

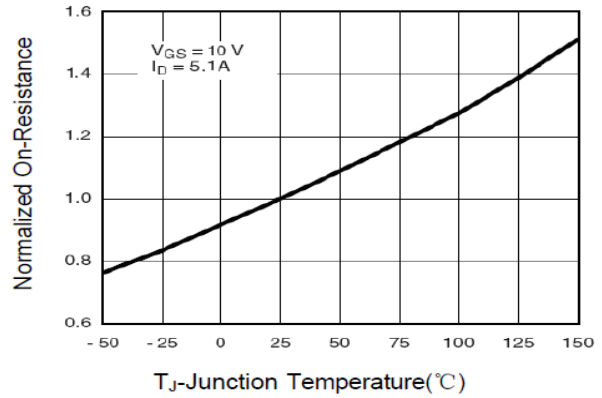


Figure 5 On-Resistance vs.  $V_{GS}$

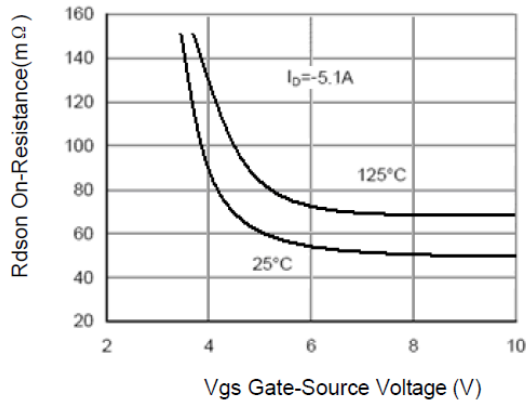


Figure 6 Body Diode Forward Voltage

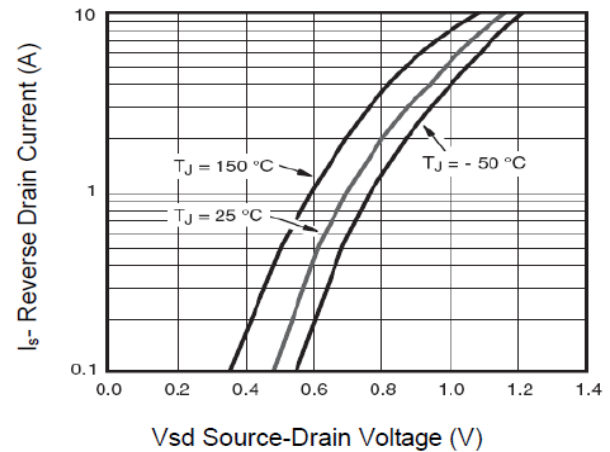


Figure 7 Gate-Charge Characteristics

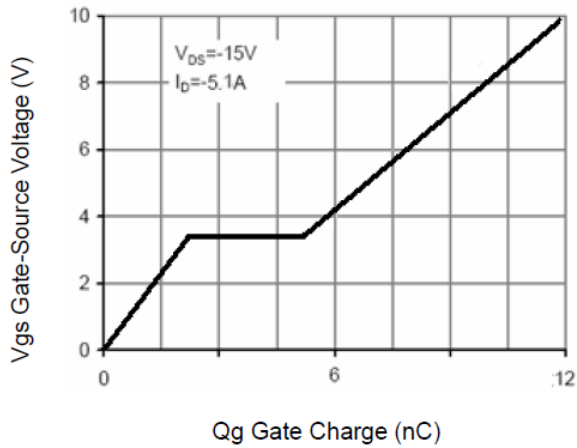


Figure 8 Capacitance Characteristics

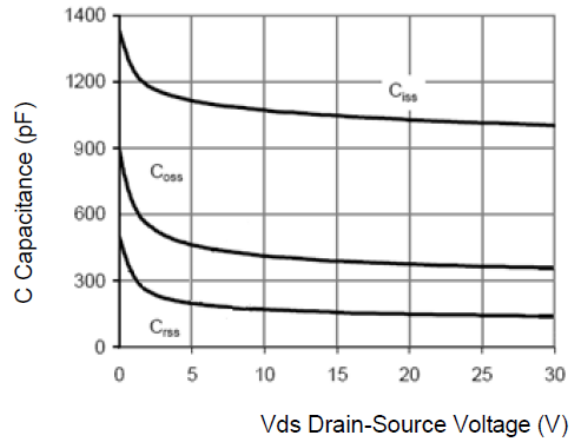


Figure 9 Safe Operation Area

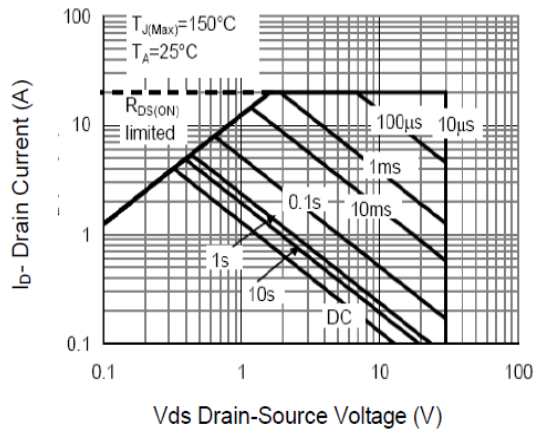


Figure 10 Transient Thermal Impedance

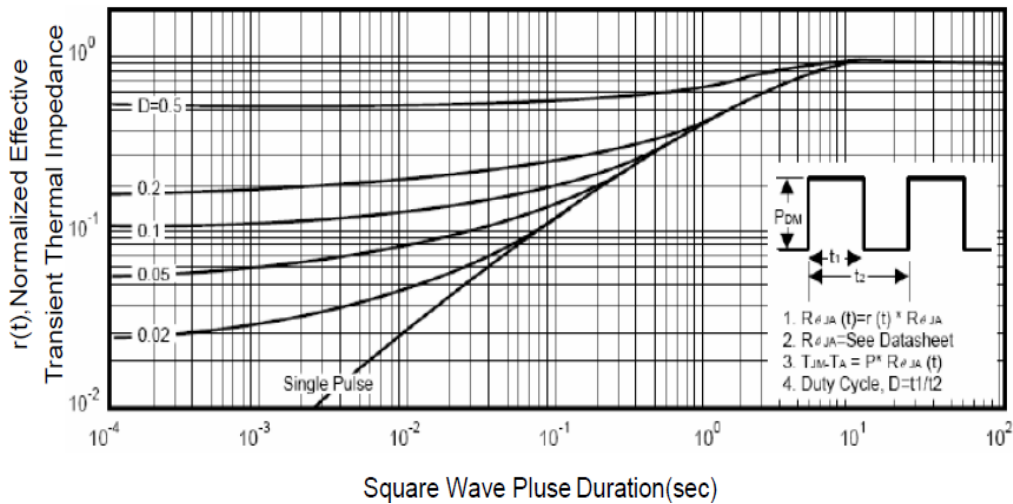
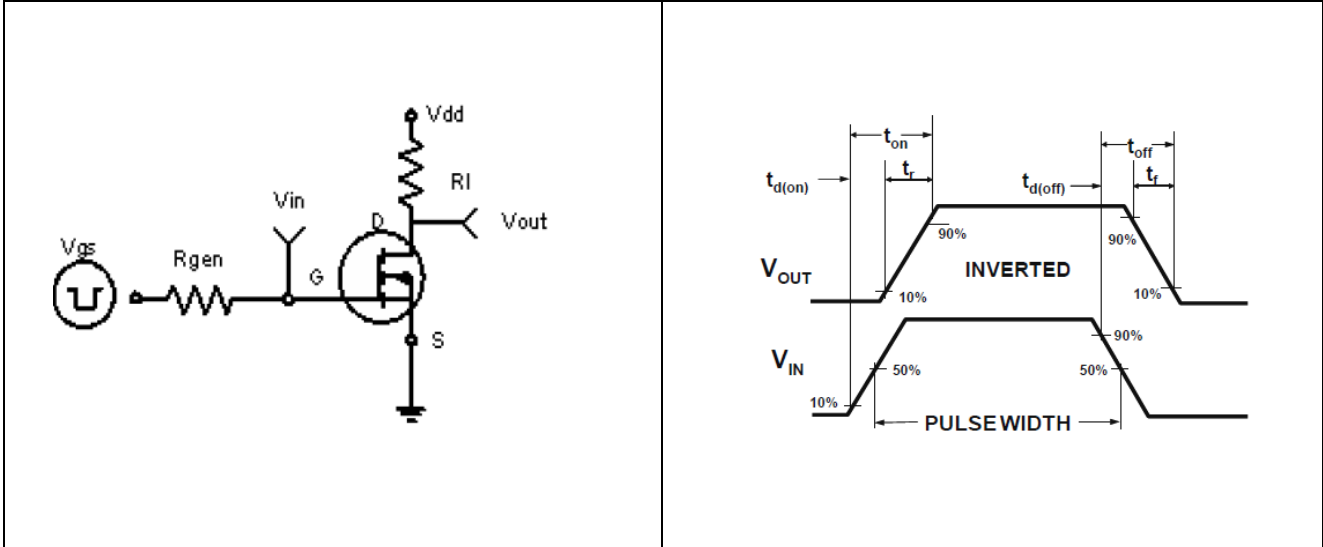
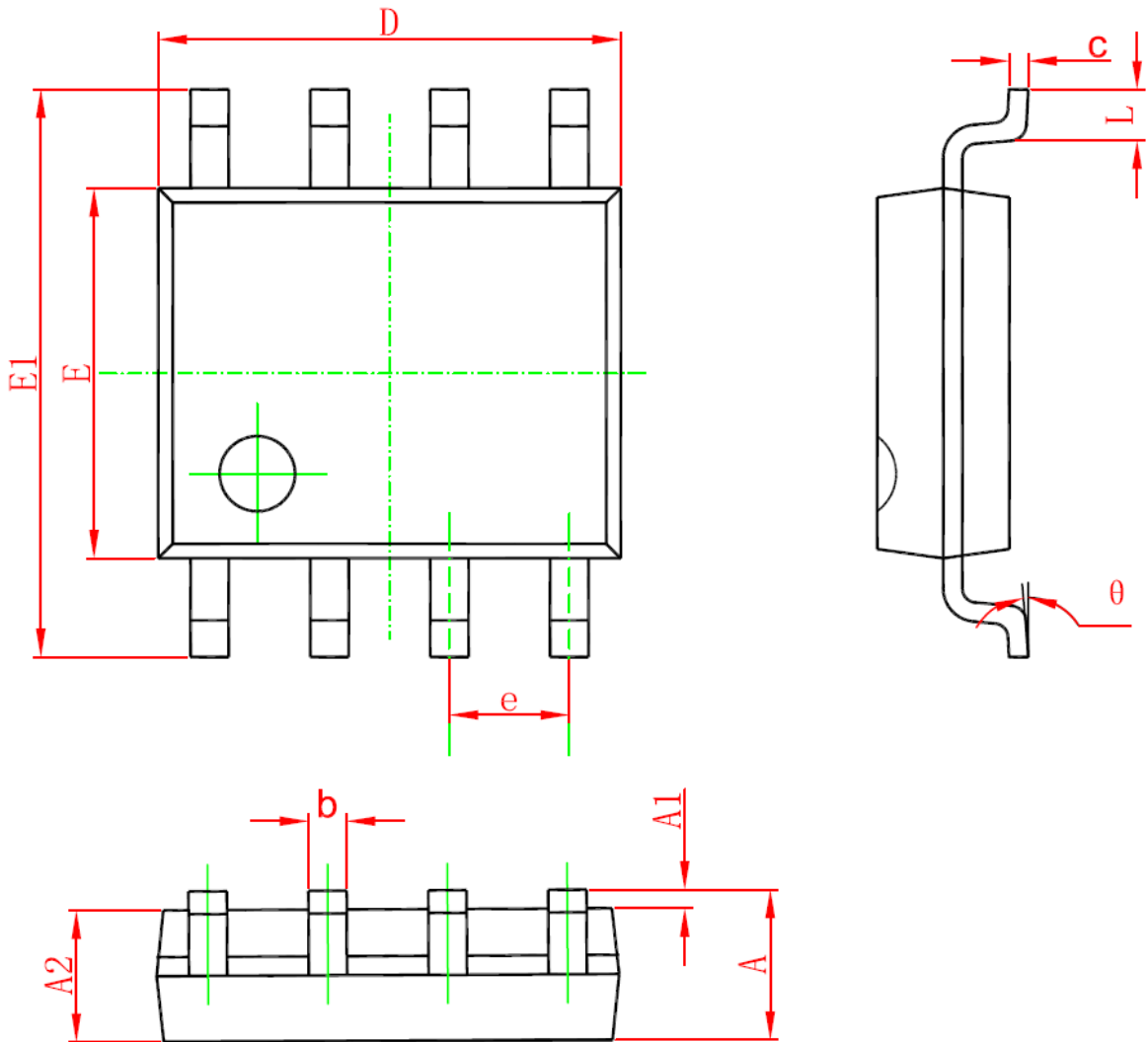


Figure B: Resistive Switching Test Circuit and Waveform



### SOP-8 PACKAGE IN FORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

**NOTE:**

1. Exceeding the maximum ratings of the device in performance may cause damage to the device, even the permanent failure, which may affect the dependability of the machine. Please do not exceed the absolute maximum ratings of the device when circuit designing.
2. When installing the heat sink, please pay attention to the torsional moment and the smoothness of the heat sink.
3. MOSFETs is the device which is sensitive to the static electricity, it is necessary to protect the device from being damaged by the static electricity when using it.
4. Shanghai Jerrett reserves the right to make changes in this specification sheet and is subject to change without prior notice.